



[10191/955]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANTS: Joerg SCHAEFER et al.

SERIAL NO.: 09/238,262

FILED: January 27, 1999

TITLE: METHOD OF PRODUCING STRUCTURED WAFERS

ART UNIT: 1746

EXAMINER: Anita K. Alanko

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

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TC 1700

**PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.114**

Sir:

In response to the Final Office Action dated August 14, 2001, please reconsider the above identified application based on at least the following:

**IN THE CLAIMS:**

Please add new Claims 10 - 13 as follows:

-- 10. (New) A method of producing a micromechanical sensor arrangement, comprising the steps of:

providing a single material wafer having a surface and edge areas;

dividing the surface of the wafer into positive areas, to be subsequently etched in a wet chemical etching process, and negative areas including the edge areas of the wafer;

providing the negative areas with a passivation layer to protect the negative areas from the subsequent wet chemical etching process;

etching the wafer in the wet chemical etching process; and

removing the passivation layer.